Inventor:

Paul A. Morgan

Title:

Methods of Cleaning Surfaces of Copper-Containing Materials, and Methods

of Forming Openings to Copper-Containings Substrates

Assignee:

Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is

directed to the United States patents and other references listed on the attached

Form PTO-1449. No admission is made regarding whether all the submitted

references are prior art.

The listed references were cited by, or submitted to, the Office in the

parent, co-pending application of the above-identified application. The above-

identified application is a continuation application of co-pending application Serial

No. 09/579,333, filed May 25, 2000. Such prior disclosure is sufficient for the

above-identified application as far as copies of the references are concerned.

37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: Octobre 10, 2003 By:

Form PTO-14	49			U.S. I	DEPARTMENT OF COMME	RCE ICE	ATTY. DOCKET NO. MI22-2411			SERIAL NO. 09/579,333		
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U.S. PATENT DOCUMENTS												
*Examiner Initial		Document Number		Date	N	Name		Class	Subclass		Filing Date If Appropriate	
	AA	6,232	2,228 B1	05-2001	Kwag et al.	g et al.					=	
	AB	6,143,658		11-2000	Donnelly, Jr. et al.							
	AC	5,017,267		05-1991	Cordani							
	AD	5,213,622		05-1993	Bohling et al.							
	AE	5,382,296		01-1995	Anttila							
	AF	5,863,344		01-1999	Nam							
	AG	6,136,767		10-2000	Hineman et al.							
	АН	5,633,121		05-1997	Namiki et al.	amiki et al.						
	AI	4,938,257		07-1990	Morris							-
	AJ	6,083,840		07-2000	Mravic et al.							
	AK	5,681,398		10-1997	Muraoka							
	AL	3,831,265		08-1974	Louzon et al.							
		1		T	FOREIGN PATENT DOCU	MEN	TS	1				
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U.S. PATENT DOCUMENTS											
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate			
***	AA	6,361,712	03/02	Honda et al.		-					
	AB	6,391,794	05-02	Chen et al.							
	AC	6,319,543	11-01	Soutar et al.							
	AD	5,861,076	01/99	Adlam et al.							
	AE	6,541,391 B2	04-2003	Smith et al.							
	AF	6,589,882 B2	07-2003	Andreas et al.							
	AG										
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